

IN THE CLAIMS:

Please amend claim 6 as follows:

Claims 1-5 (Cancelled).

Claim 6 (Currently Amended): A semiconductor device provided with a mounting leg to be inserted into a mounting hole of a base plate, characterized in that said mounting leg includes an elastic vertical leg body which extends downward from a body of said case and a contact portion to be brought into elastic contact with a lower edge of said mounting hole at a lower part of said leg body, and said contact portion has a slope which slopes ~~out downward~~ outward and downward from the side of said vertical leg body.

Claim 7 (Original): A semiconductor device according to claim 6, characterized in that the sloping angle of said slope to a horizontal plane is 45° or less.

Claim 8 (Original): A semiconductor device according to claim 6, characterized in that it is provided with an attachment stabilizing piece which extends outwards from the side of the lower portion of the semiconductor device body and a horizontal lower face which is brought into contact with a surface of the base plate when the semiconductor device is attached to the base plate.

Claim 9 (Original): A semiconductor device according to claim 8, characterized in that said attachment piece is arranged on the side perpendicular to said contact portion.

Claim 10 (Original): A semiconductor device according to claim 8, characterized in that a floatage suppressing piece is provided on the side surface of the case body.

Claim 11 (Original): A semiconductor device according to claim 8, characterized in that said floatage suppressing piece is formed in contact with a chassis or frame.

Claim 12 (Original): A semiconductor device according to claim 9, characterized in that said case is molded monolithically by a transfer mold.